

WHAT IS CLAIMED IS:

1. A wiring board comprising:
  - interlayer insulating films;
  - multilayer wiring films, each being provided at one of the interlayer insulating films or between two of the interlayer insulating films;
  - interlayer-connection conductor films, each extending through at least one of the interlayer insulating films and providing an electrical connection between at least two of the interlayer insulating films;
  - at least one bare semiconductor integrated circuit device;
  - a first shield wiring film provided above the semiconductor integrated circuit device and a second shield wiring film provided below the semiconductor integrated circuit device; and
  - a plurality of shield interlayer-connection conductor films that are provided so as to surround the semiconductor integrated circuit device and that provide electrical connections between the first shield wiring film and the second shield wiring film, each shield interlayer-connection conductor film extending through at least one of the interlayer insulating films.

2. A wiring board comprising:

interlayer insulating films;

multilayer wiring films, each being provided at one of the interlayer insulating films or between two of the interlayer insulating films;

interlayer-connection conductor films, each extending through at least one of the interlayer insulating films and providing an electrical connection between at least two of the interlayer insulating films;

at least one bare semiconductor integrated circuit device;

a first shield wiring film on which the semiconductor integrated circuit device is directly mounted;

a second shield wiring film provided so as to oppose the first wiring film with the semiconductor integrated circuit device interposed therebetween; and

a plurality of shield interlayer-connection conductor films that are provided so as to surround a periphery of the semiconductor integrated circuit device and that provide electrical connections between the first shield wiring film and the second shield wiring film, each shield interlayer-connection conductor film extending through at least one of the interlayer insulating films.

3. The wiring board according to one of claims 1 and 2,

wherein the first and second shield wiring films have a gap therebetween, the gap being smaller than one half a wavelength  $\lambda_g$  of an electromagnetic wave to be prevented from radiating.

4. The wiring board according to one of claims 1 to 3, wherein at least one of the shield wiring films has a hole, a diameter or a longitudinal side of the hole being smaller than one half a wavelength  $\lambda_g$  of an electromagnetic wave to be prevented from radiating.

5. The wiring board according to one of claims 1 to 4, wherein the first and second shield wiring films and the shield interlayer-connection conductor films define a shield cage having an rectangular-parallelepiped inner space with height  $a$ , width  $b$ , and length  $c$ , where  $a \leq b \leq c$ , and a wavelength  $\lambda_g$  of an electromagnetic wave to be prevented from radiating satisfies a relationship:

$$\lambda_g > 2 / [ \{ (1/b)^2 + (1/c)^2 \}^{1/2} ] .$$

6. A circuit module comprising:  
the wiring board according to one of claims 1 to 5;  
at least one semiconductor integrated circuit device provided on the wiring board; and  
at least one passive component provided on the wiring

board.